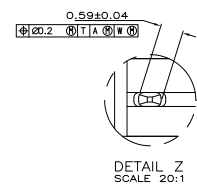
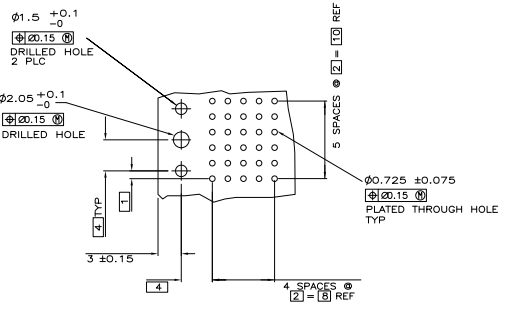
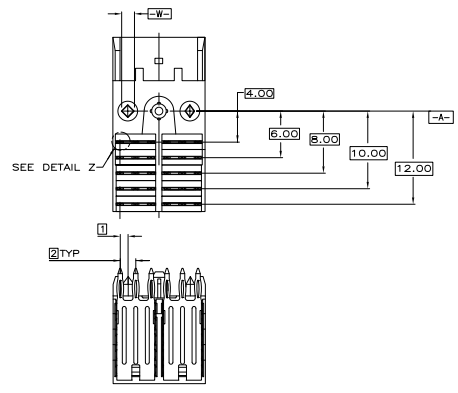
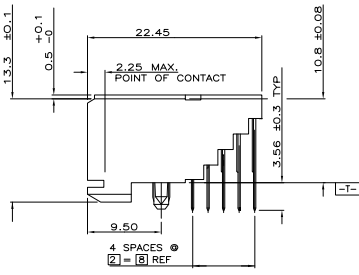
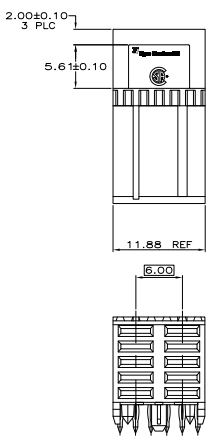


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REV	DATE	DESCRIPTION	BY	CHK	APP
AD	00		JL		
		REVISED PER ECO-08-009182			

△ HOUSINGS MATERIAL: LIQUID CRYSTAL POLYMER.
 △ CONTACT MATERIAL: COPPER ALLOY
 △ CONTACT FINISH:
 UNDERPLATE (ENTIRE CONTACT):
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290
 ON MATING SURFACES:
 FLASH GOLD PER ASTM B 488, OVER
 0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR
 0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.
 ON LEADS:
 0.00127 MIN TIN-LEAD OVER UNDERPLATE.
 LUBRICATION (MIN MATING SURFACES):
 SURFACE CONDITIONER AFTER PLATING.



RECOMMENDED CIRCUIT PATTERN
 PER IPC-D300 TYPE II, CLASS C
 (COMPONENT SIDE)

FINISH	NO OF POSN	PART NUMBER
		536649-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		BY: SHEY	DATE: 2-18-08	YIP Electronics Corporation
DRAWN BY: JLL		BY: MELLUMES	DATE: 2-24-08	Harrisburg, PA 17105-3608
CHECKED BY: JLL		BY: JLL	DATE: 2-24-08	ASSEMBLY, RECEPTACLE, 5 ROW, POWER MODULE, PRESS FIT LEAD, 3.56mm LEAD LENGTH, 2-PACK, 2mm FB
APPROVED BY: JLL		DATE: 2-24-08	DRAWING NO: A100779	REVISED TO: 0
CUSTOMER DRAWING		DATE: 2-1	REV: 1	BY: JL